

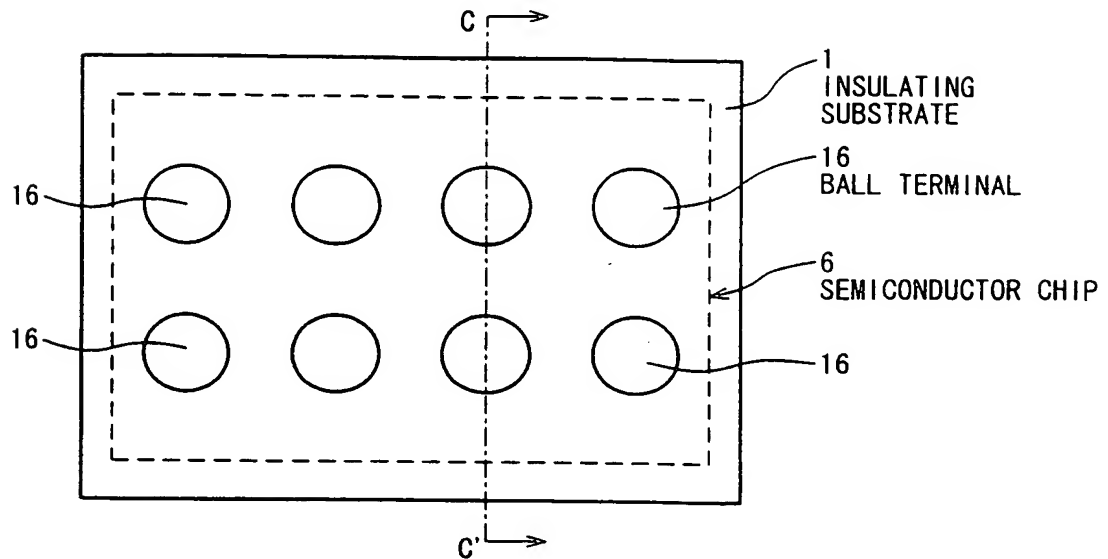
Title: METHOD OF FABRICATING A  
WIRING BOARD UTILIZING A  
CONDUCTIVE MEMBER HAVING A  
REDUCED THICKNESS

Inventor(s): Akira CHINDA et al.

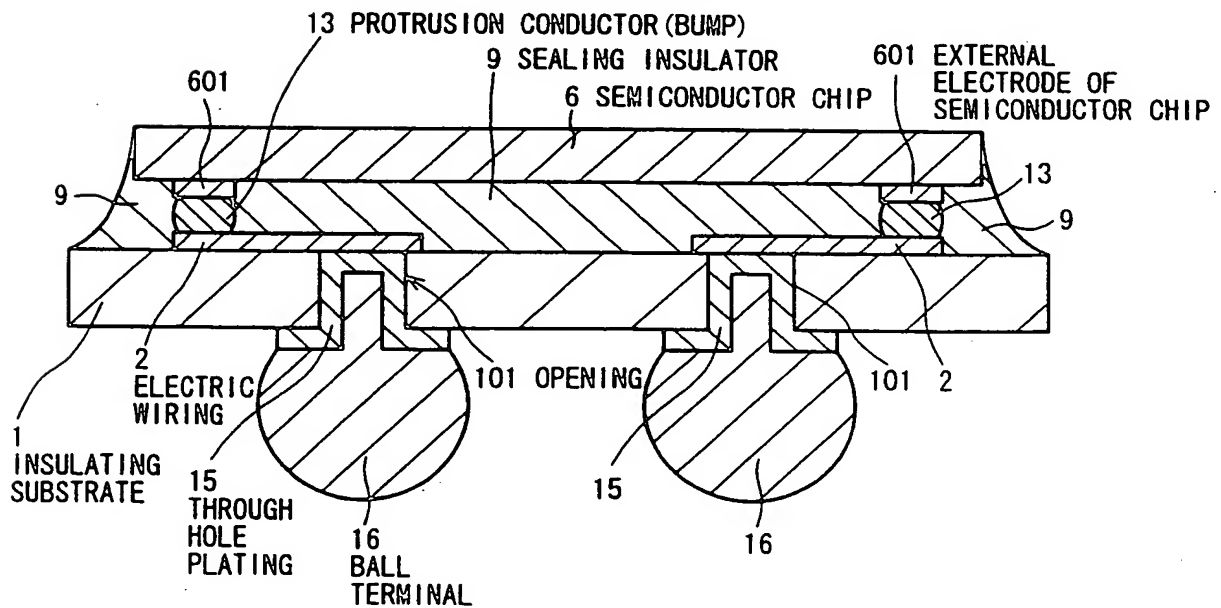
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*FIG. 1A PRIOR ART*



*FIG. 1B PRIOR ART*



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*FIG. 2 PRIOR ART*

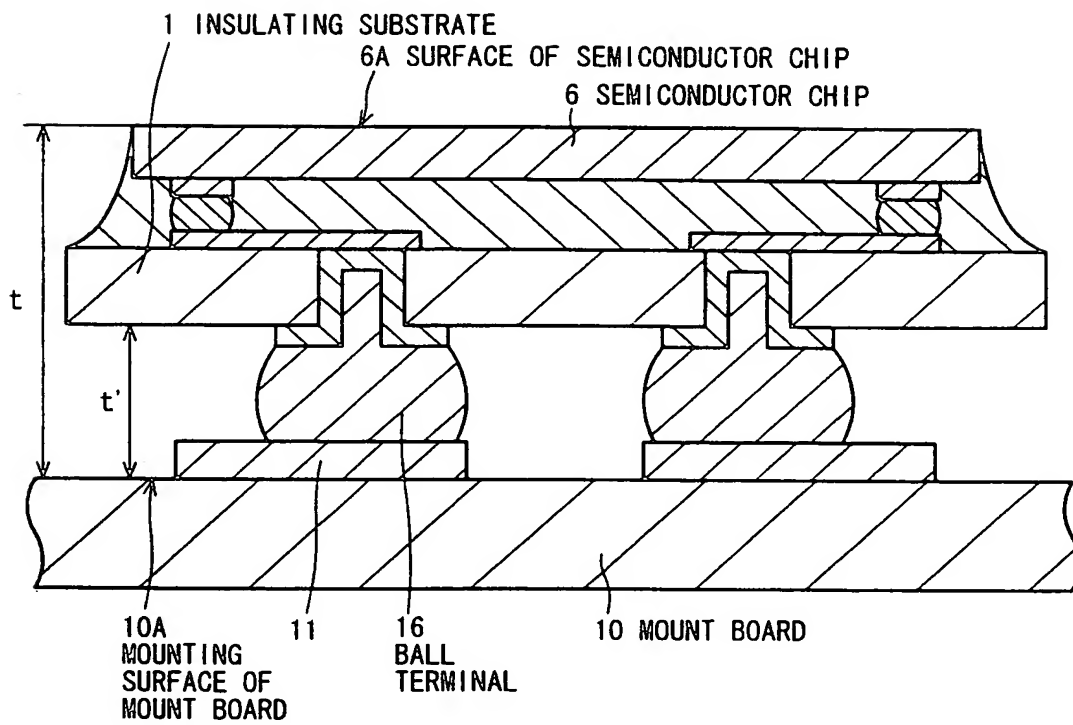
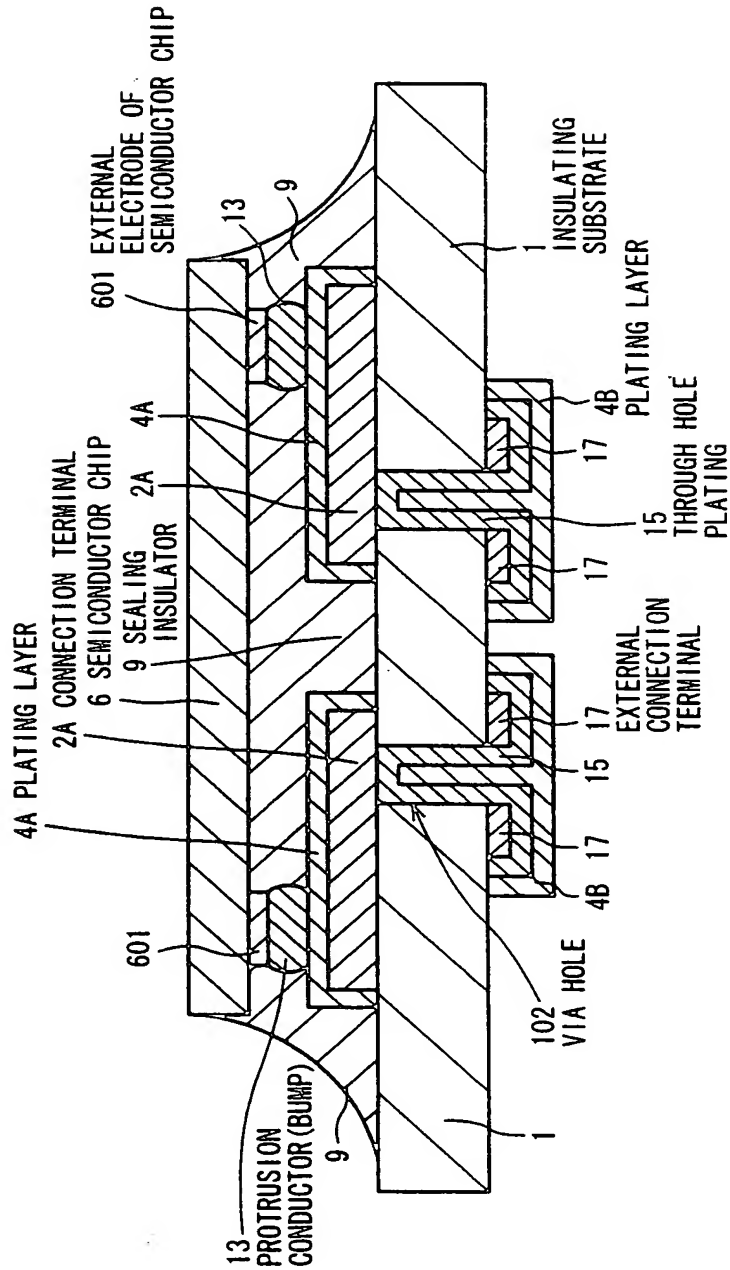


FIG. 3 PRIOR ART

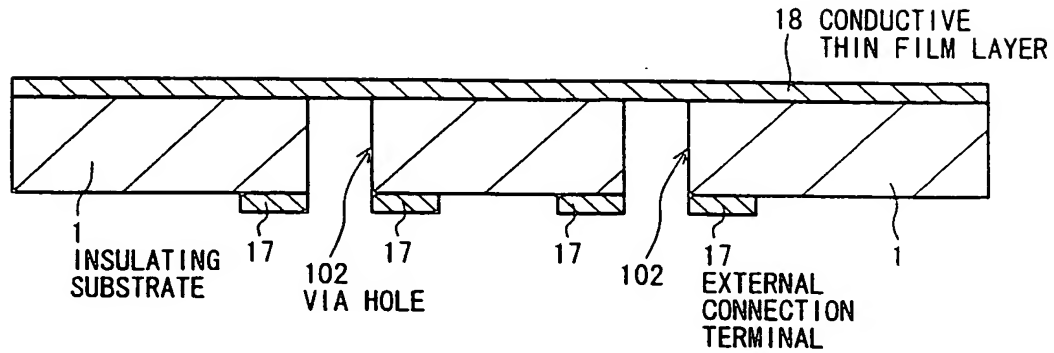


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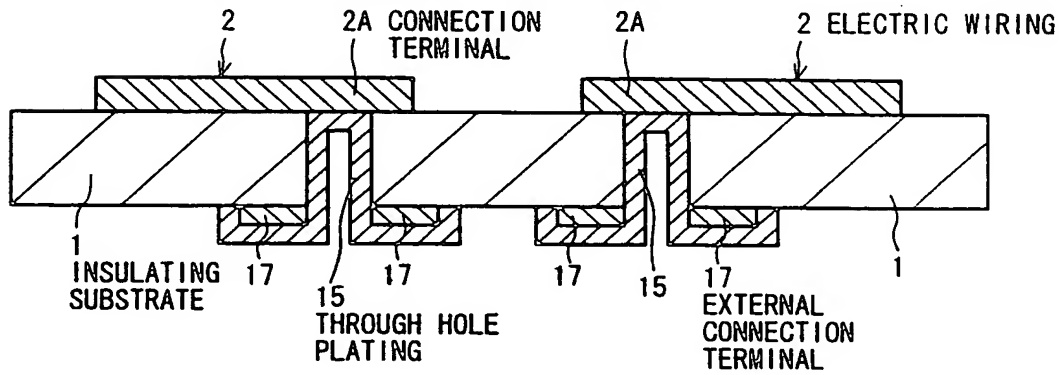
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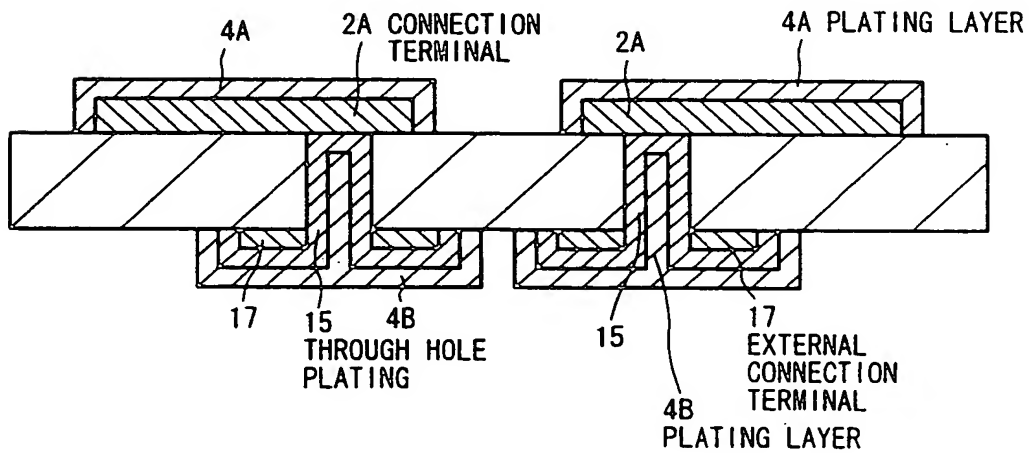
*FIG. 4A PRIOR ART*



*FIG. 4B PRIOR ART*



*FIG. 4C PRIOR ART*

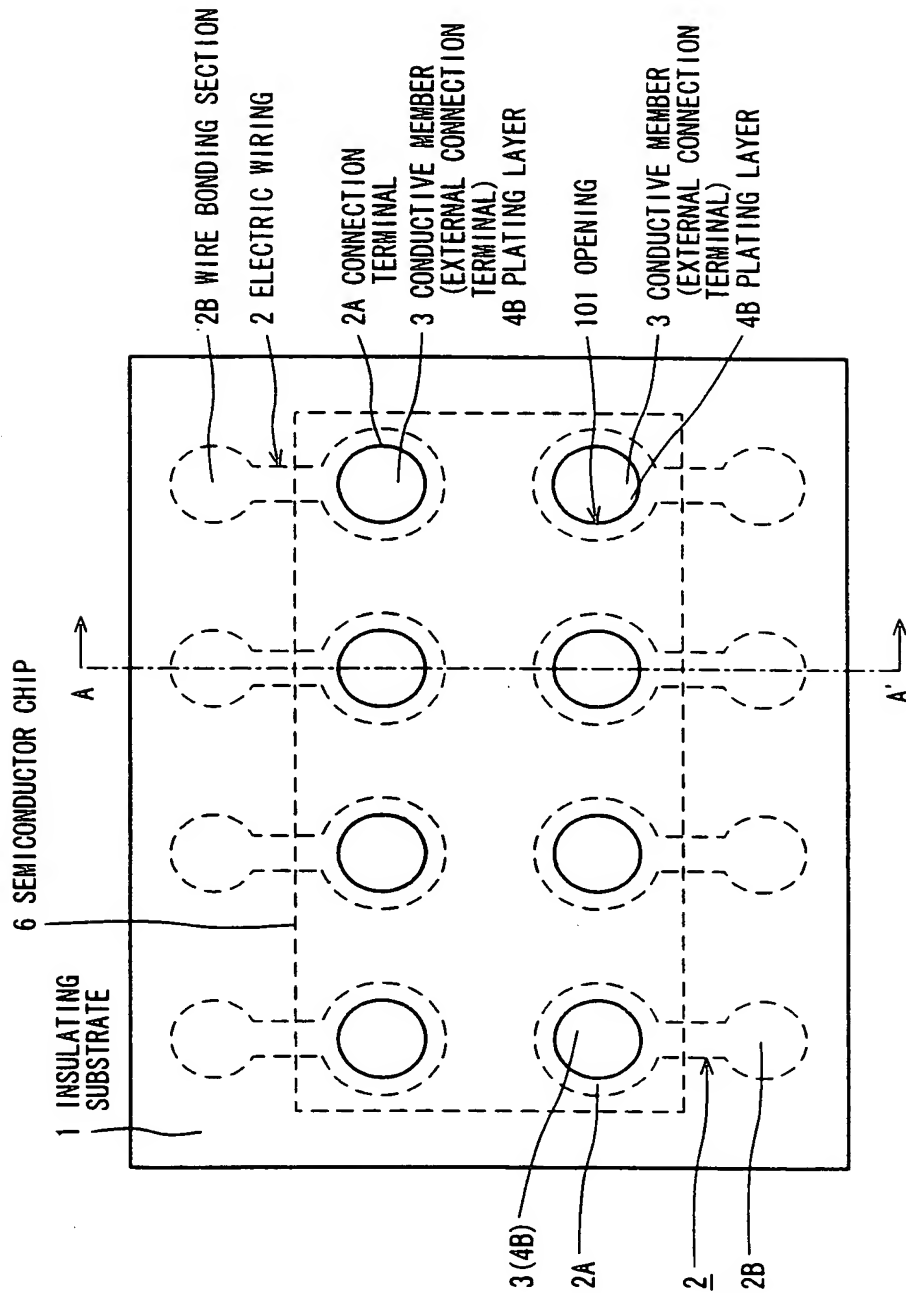


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FIG. 5

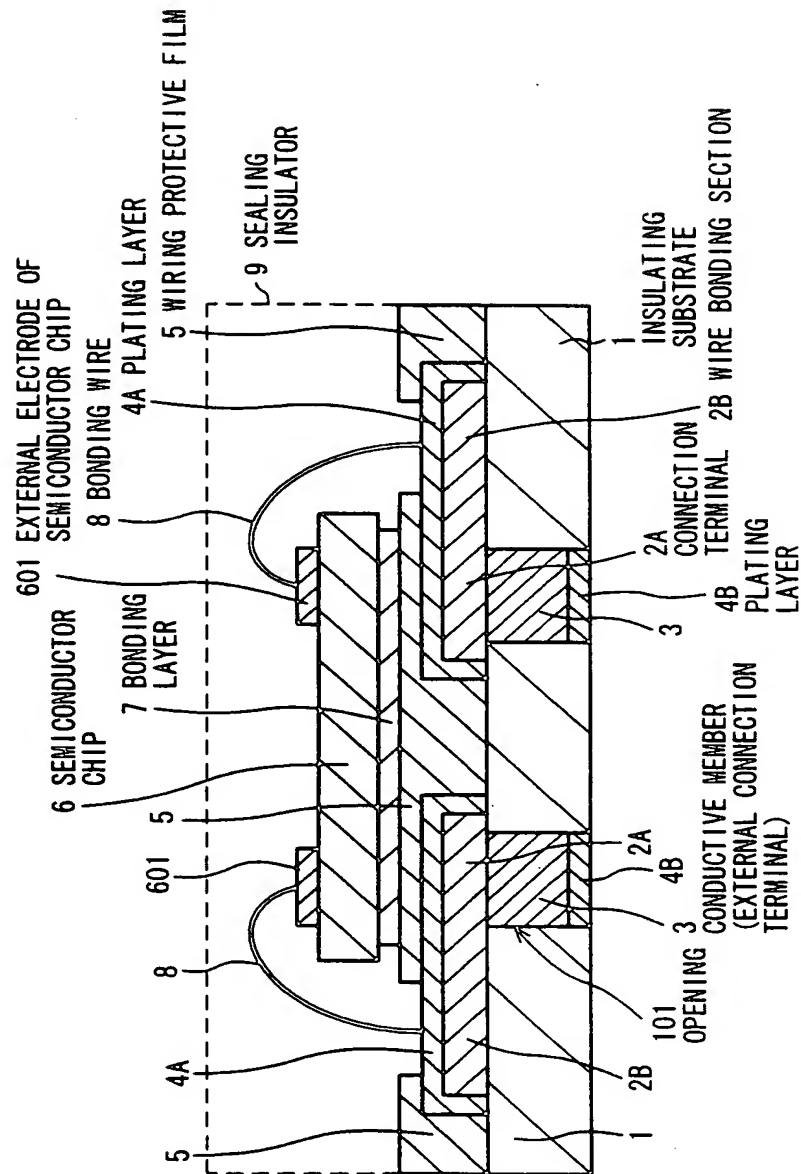


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FIG. 6

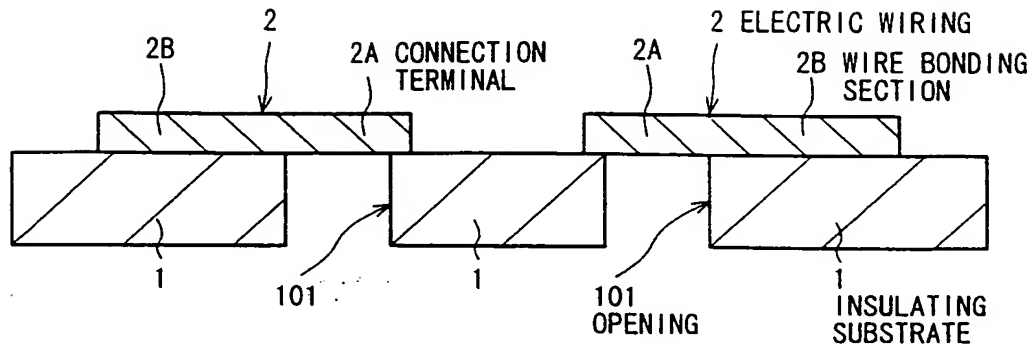


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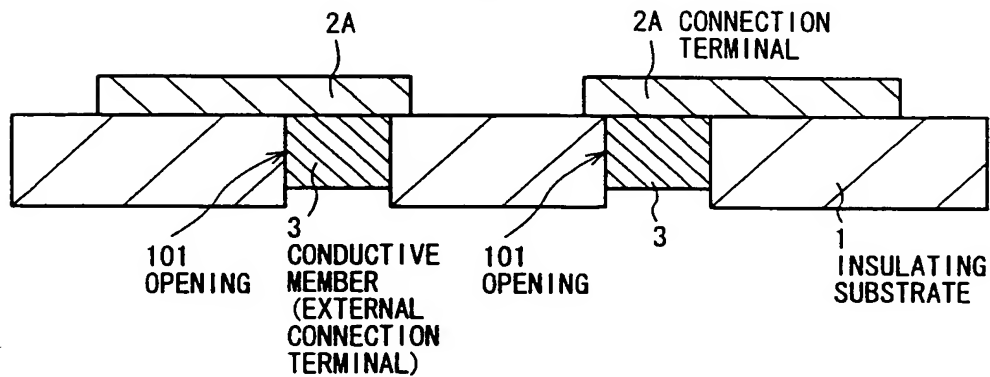
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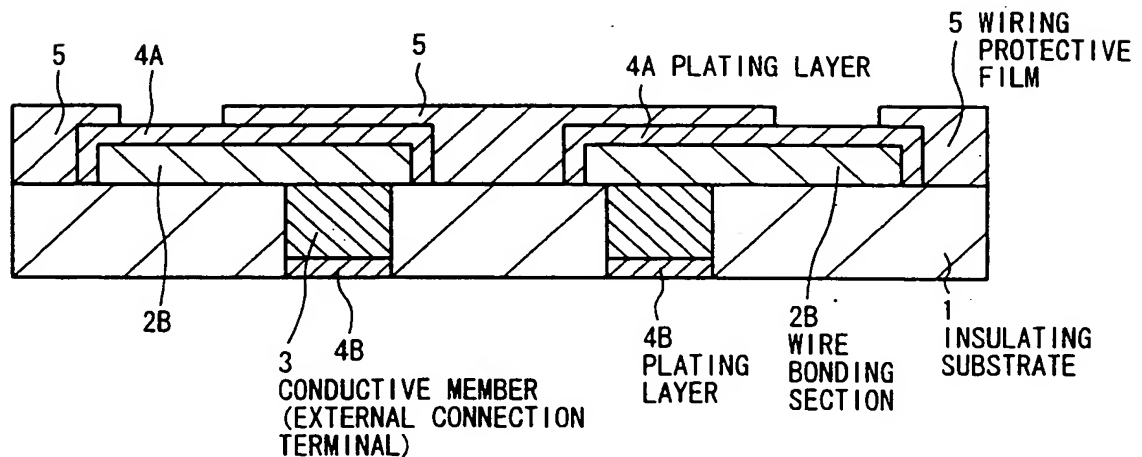
**FIG. 7A**



**FIG. 7B**



**FIG. 7C**



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FIG. 1 METHOD OF FABRICATING A

*FIG. 8*

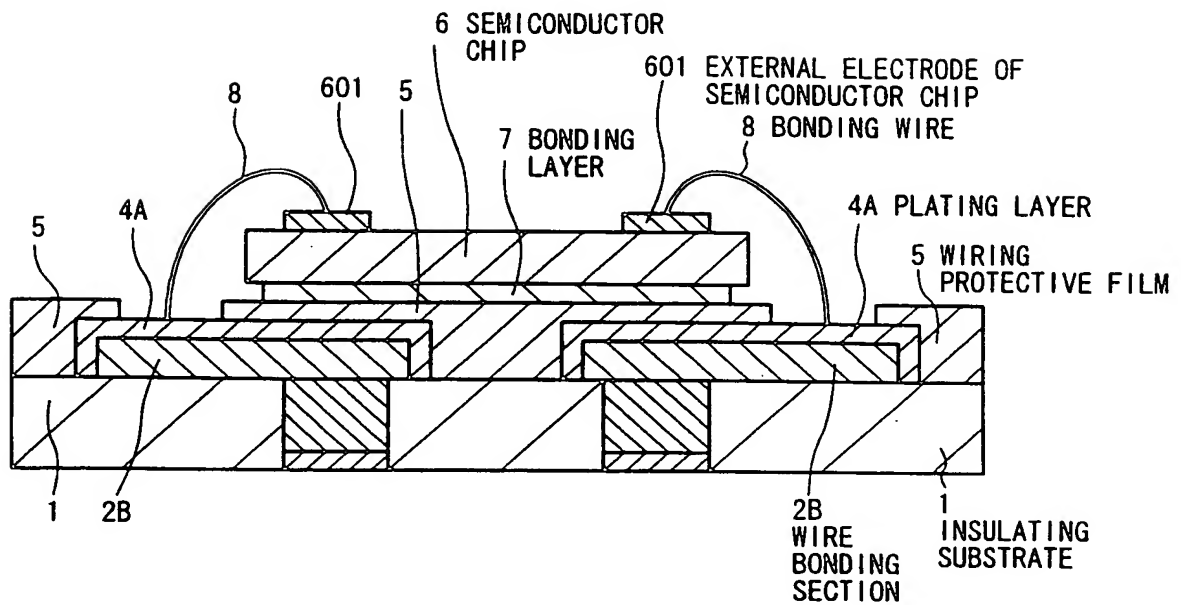
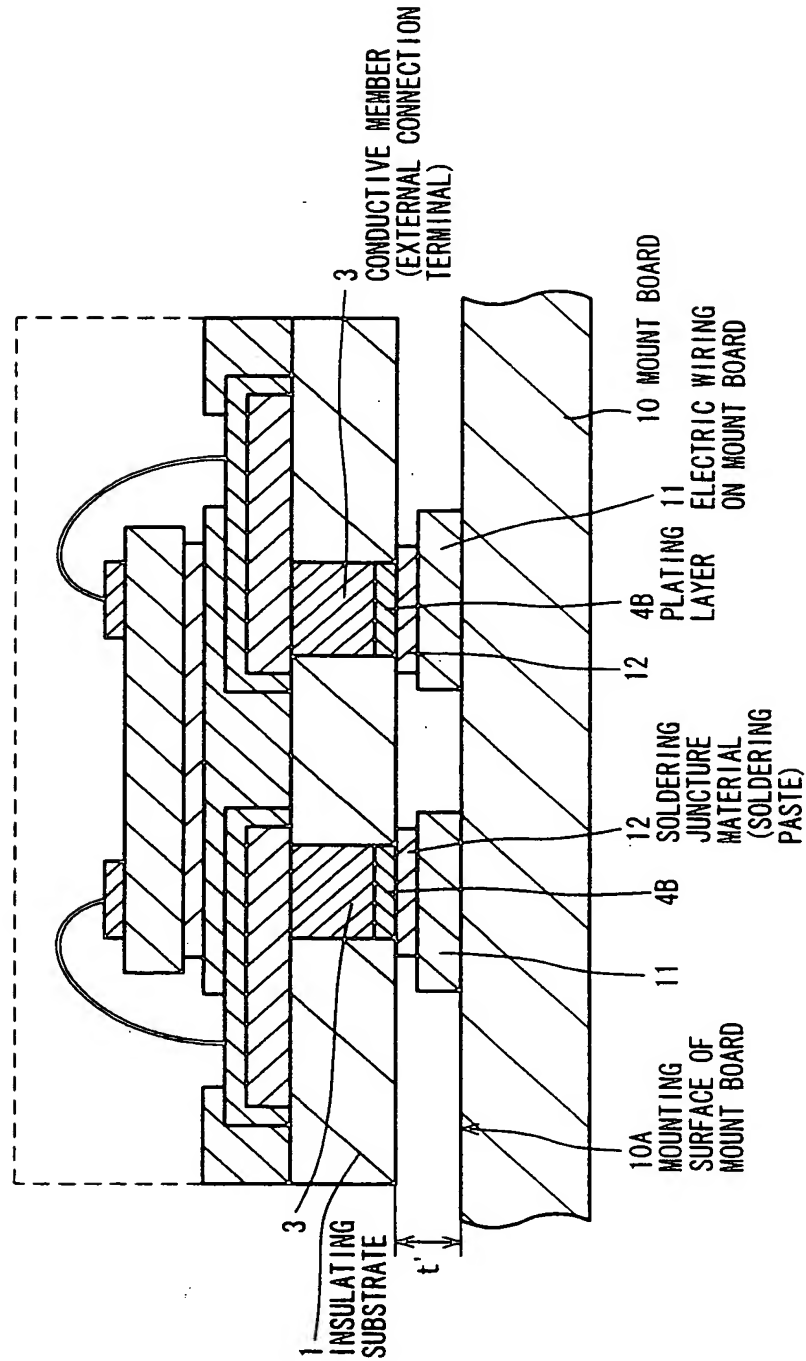




FIG. 9

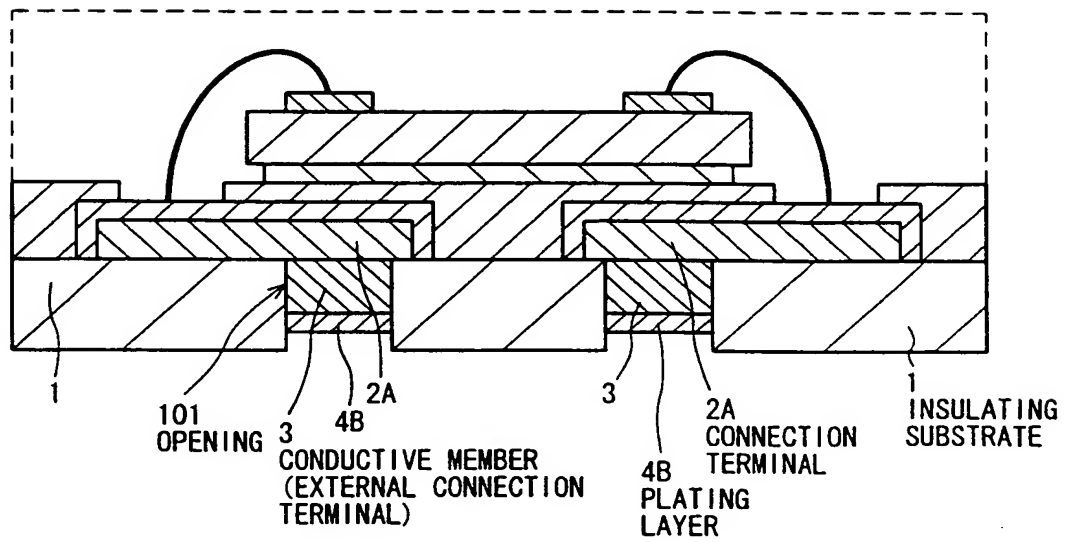


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**FIG. 10**

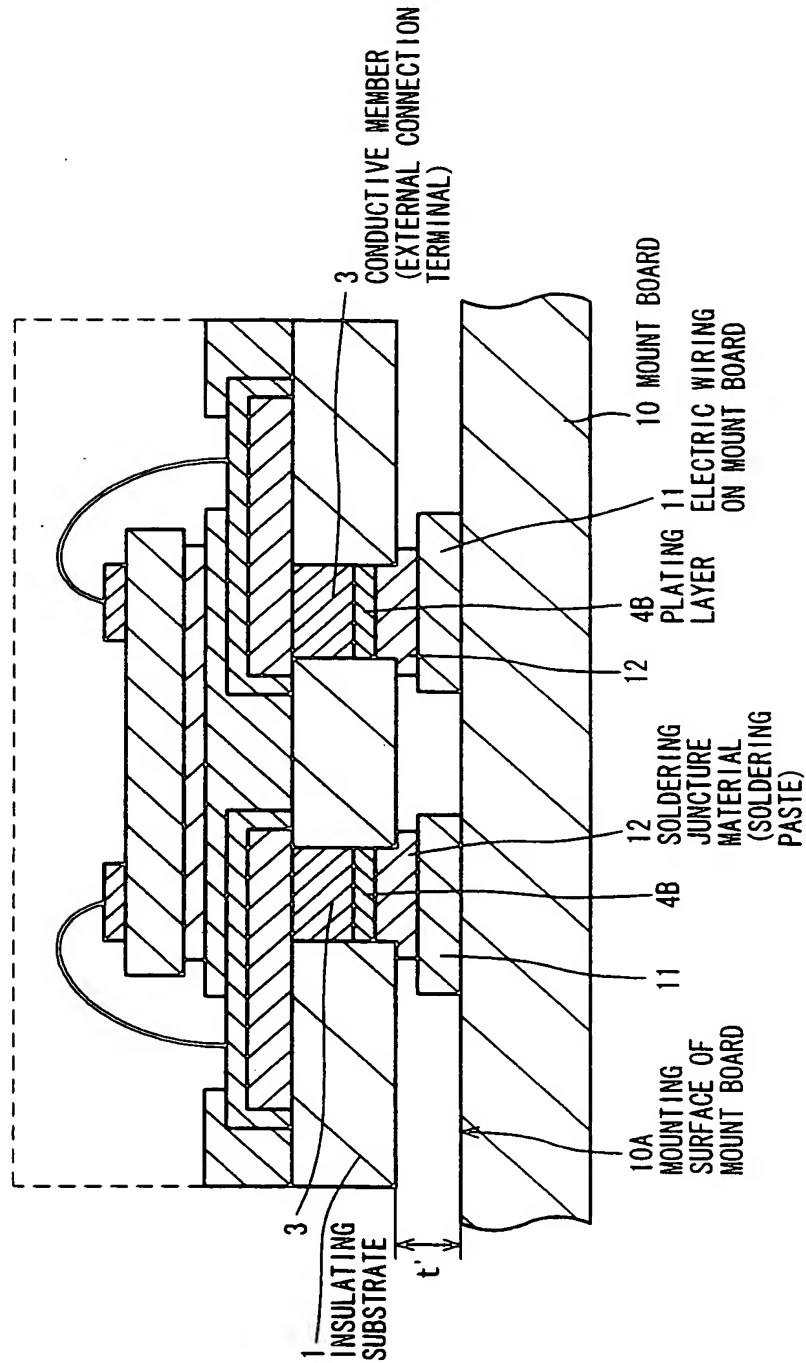


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FIG. 11



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**FIG. 12**

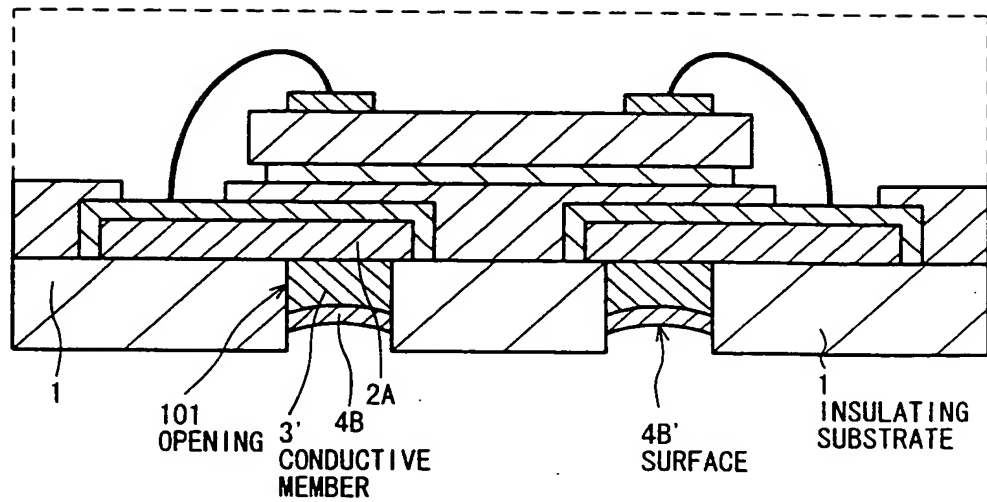


FIG. 13

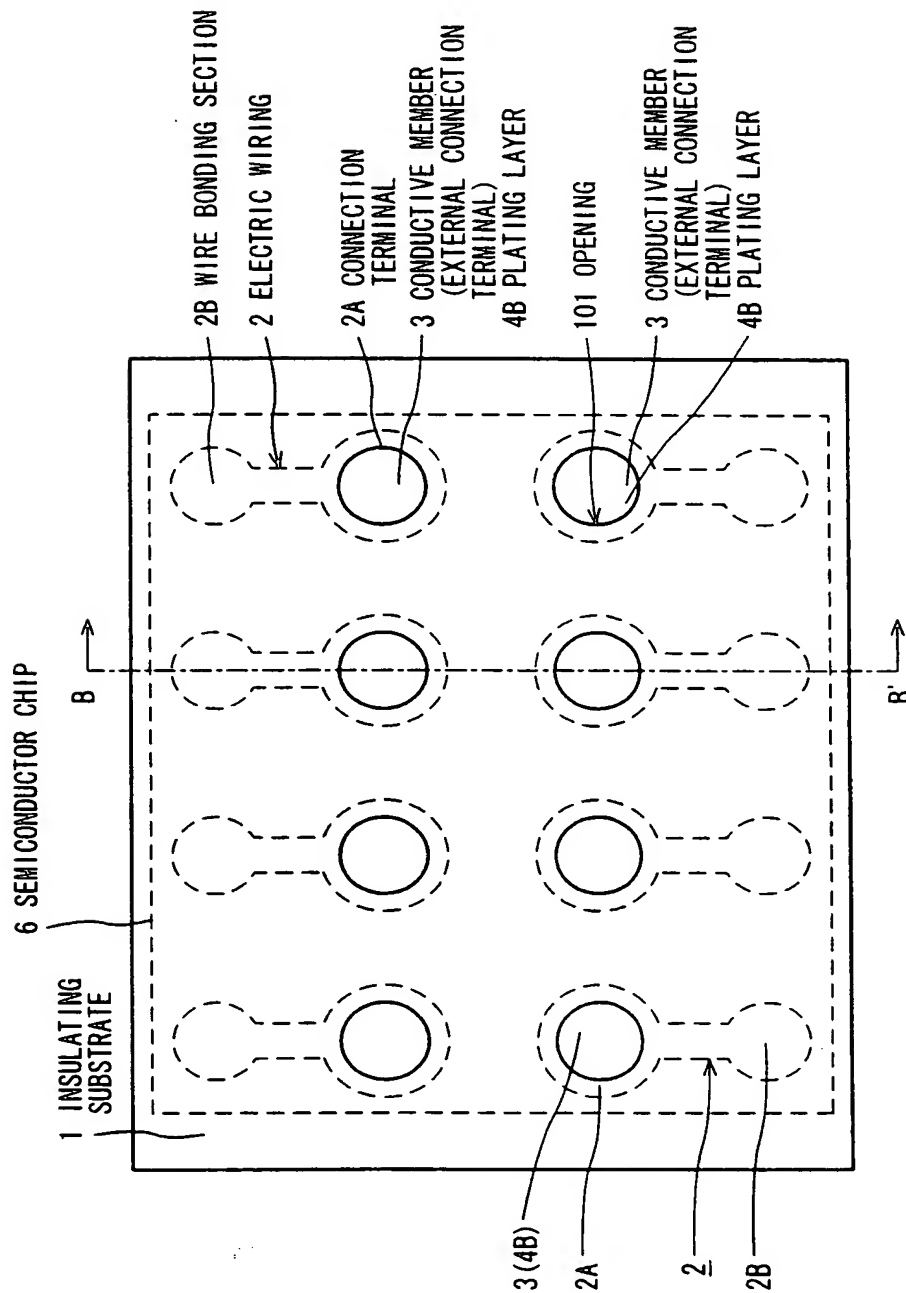
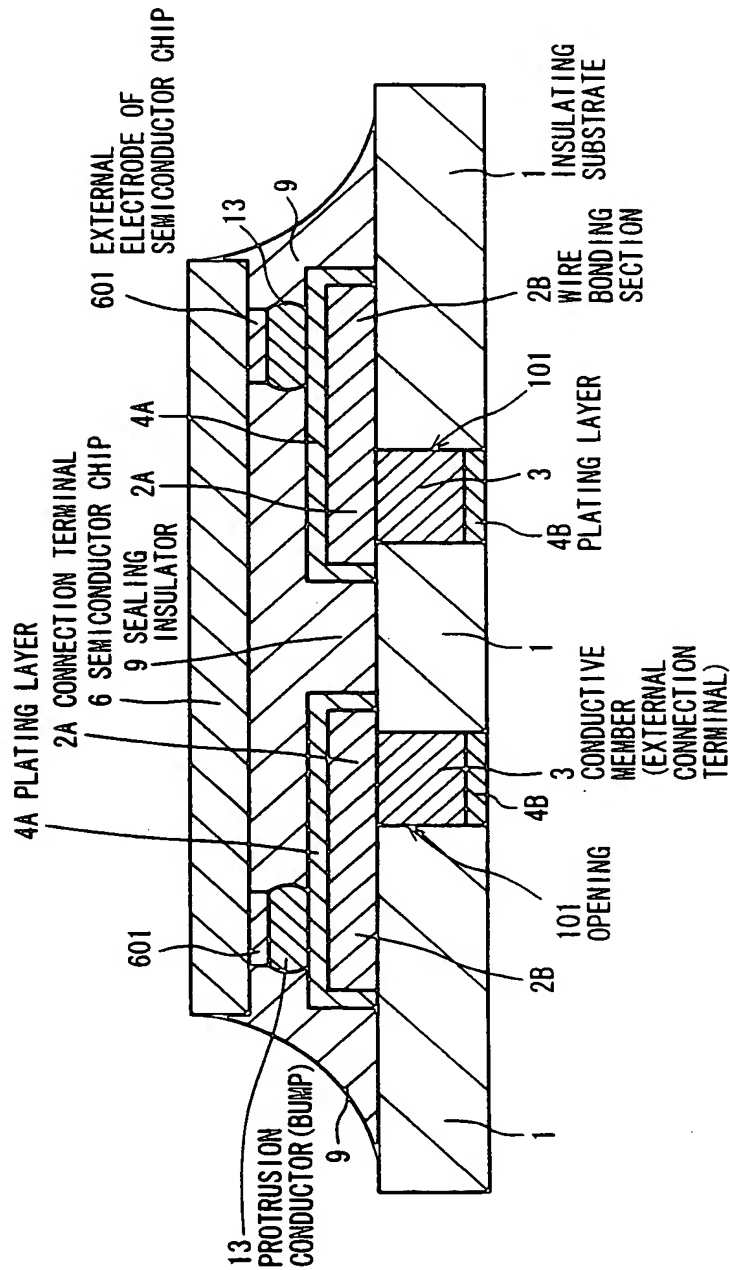


FIG. 14

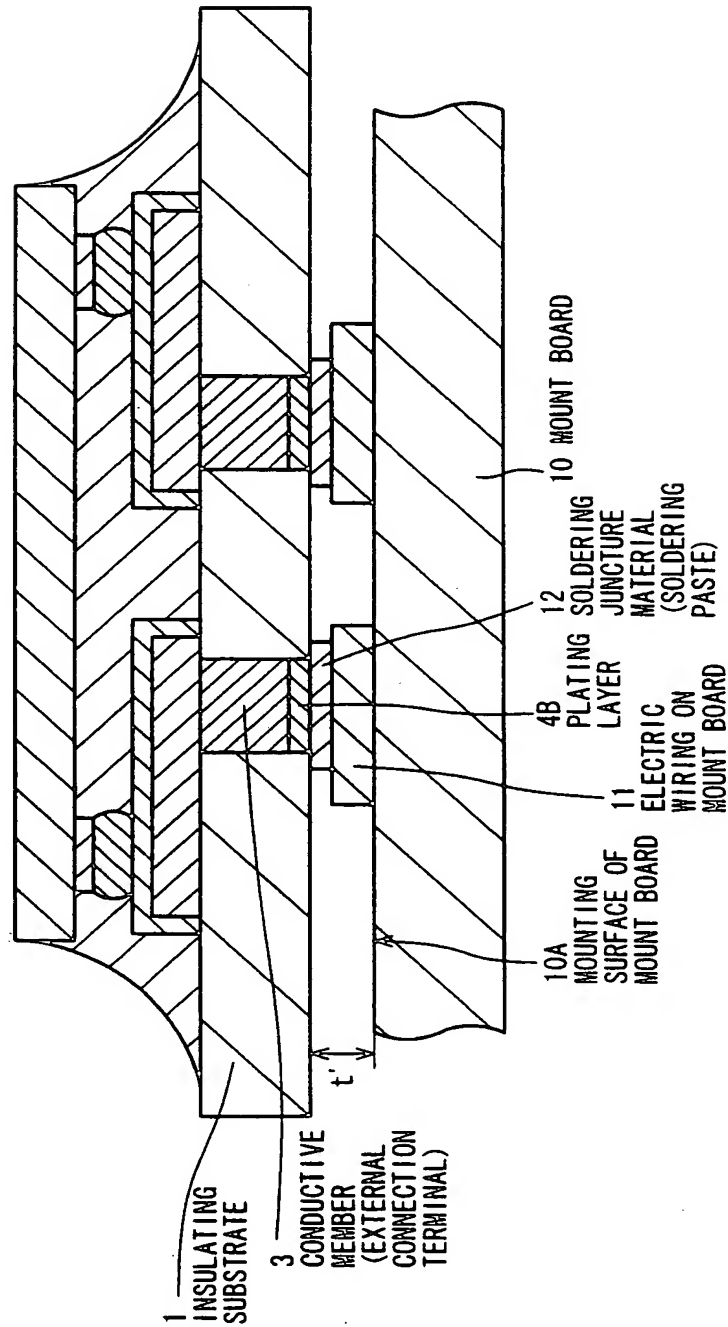


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FIG. 15



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FIG. 16

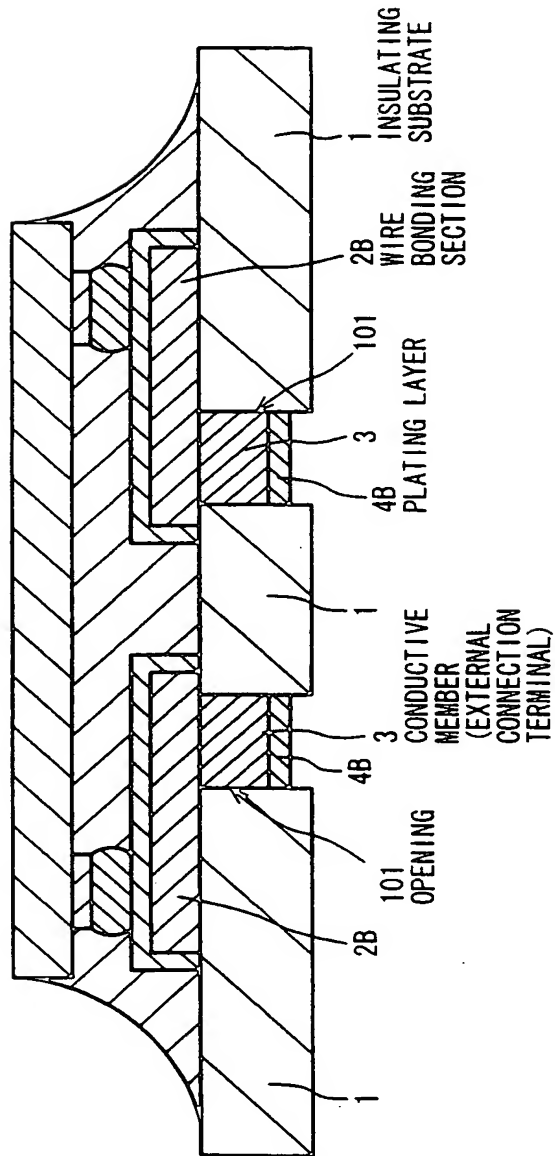




FIG. 1 is a cross-sectional view of a wire bonding section and an opening conductive member. The wire bonding section (left) shows a wire (101) bonded to a substrate (1) with a bonding member (2B). The opening conductive member (right) shows an opening (101) in a substrate (1) with a conductive member (2B) and a surface layer (4B'). Both sections show a hatched layer (3') and a surface layer (4B').

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FIG. 18

